

Appl. No. 09/744,424
Response Under 37 C.F.R. § 1.116
Expedited Procedure
Examining Group 2827
Amdt. dated April 14, 2003
Reply to Office Action of February 13, 2003

This listing of claims will replace all prior versions, and listings of claims in the application.

Listing of Claims:

Claims 1 – 115 (Cancelled)

116. (Currently Amended) A printed wiring board-forming sheet comprising an insulating resin sheet, wherein the insulating resin sheet is made of at least one material selected from the group consisting of polyimide, polyester, polypropylene, polyphenylene sulfide, polyvinylidene chloride, ethylene-vinyl alcohol copolymer, and bismaleimide triazine (BT) resin, having a through hole inserted and filled with a conductive metal chip of substantially the same shape as the hole, wherein the conductive metal chip is formed by punching at least one conductive metal sheet selected from the group consisting of a solder sheet, a solder-plated metal sheet and a copper alloy sheet.

117. (Previously Added) The printed wiring board-forming sheet as claimed in claim 116, wherein a conductive material layer is formed on at least one surface of the insulating resin sheet having a through hole inserted and filled with a conductive metal chip, said conductive material layer and the conductive metal chip being connected electrically with each other.

118. (Previously Added) The printed wiring board-forming sheet as claimed in claim 117, wherein the conductive material layer is formed by a foil of a metal or a metal-alloy or a wiring pattern.

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119. (Cancelled)

120. (Cancelled)

Claims 121 – 134 (Cancelled)

135. (Cancelled)

136. (Cancelled)